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Atty. Docket No.
FIS9-2000-0134US3

Application No.

Applicant
H. BERNHARD FOGGE

Filing Date

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U.S. PATENT DOCUMENTS

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
12	4 6 7 0 7 7 0	06/02/87	Tai			
	4 7 8 3 6 9 5	11/08/88	Eichelberger et al.			
	4 8 8 4 1 2 2	11/28/89	Eichelberger et al.			
	4 9 3 3 0 4 2	06/12/90	Eichelberger et al.			
	4 9 4 9 1 4 8	08/14/90	Bartelink			
12	5 0 1 9 5 3 5	05/28/91	Wojarowski et al.			

FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Subclass	Translation Yes	Translation No
1 0 4 1 6 2 4	10/04/00	European Patent Office				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)

12	J. Pilchowski et al., "Silicon MCM with Fully Integrated Cooling,"
	HDI Magazine, May 1998, p.48.
	J. Wolf et al., "System Integration for High Frequency Applications,"
	Intl. J. of Microelectronics and Electronic Packaging 21, 119 (1998).
	C.A. Amianto et al., "Gigabit Transmitter Array Modules on Silicon Waferboard," IEEE Transactions on Components, Hybrids and Manufacturing Technology 15, 1072 (1992).
	M. Töpper et al., "Embedding Technology—A Chip-First Approach Using BCB,"
	1997 Intl. Symposium on Advanced Packaging Materials, p. 11.

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<i>W</i>	5 3 5 3 4 9 8	10/11/94	Fillion et al.			
	5 3 7 3 6 2 7	12/20/94	Grebe			
<i>W</i>	6 1 1 0 8 0 6	08/29/00	Pogge			

FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Subclass	Translation
					Yes No

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<i>W</i>	Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.
	Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).
	Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).
<i>W</i>	R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).

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*Nick Pould**03/14/05*

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"A Novel Chip-Stack Package" - Solid State Technology, April 2002, www.solid-state.com, pp. S19-S22, Eric Beyne, IMEC, Leuven, Belgium

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